MJE13007

SWITCHMODE[™]

NPN Bipolar Power Transistor For Switching Power Supply Applications

The MJE13007 is designed for high-voltage, high-speed power switching inductive circuits where fall time is critical. It is particularly suited for 115 and 220 V SWITCHMODE applications such as Switching Regulators, Inverters, Motor Controls, Solenoid/Relay drivers and Deflection circuits.

Features

- V_{CEO(sus)} 400 V
- Reverse Bias SOA with Inductive Loads @ $T_C = 100$ °C
- 700 V Blocking Capability
- SOA and Switching Applications Information
- Standard TO-220
- Pb-Free Package is Available*

MAXIMUM RATINGS

ı	Symbol	Value	Unit			
Collector-Emitter	V_{CEO}	400	Vdc			
Collector-Base Br	V _{CES}	700	Vdc			
Emitter-Base Volta	V _{EBO}	9.0	Vdc			
Collector Current	ContinuousPeak (Note 1)	I _C	8.0 16	Adc		
Base Current	ContinuousPeak (Note 1)	I _B	4.0 8.0	Adc		
Emitter Current	ContinuousPeak (Note 1)	I _E	12 24	Adc		
Total Device Dissipation @ T _C = 25°C Derate above 25°C		P _D	80 0.64	W W/°C		
Operating and Sto	T _J , T _{stg}	-65 to 150	°C			

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.56	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	TL	260	°C

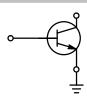
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

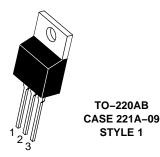
- 1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.
- *Measurement made with thermocouple contacting the bottom insulated mounting surface of the package (in a location beneath the die), the device mounted on a heatsink with thermal grease applied at a mounting torque of 6 to 8lbs.
- *For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



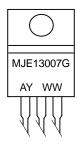
ON Semiconductor®

POWER TRANSISTOR 8.0 AMPERES 400 VOLTS – 80 WATTS





MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week

G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
MJE13007	TO-220	50 Units / Rail
MJE13007G	TO-220 (Pb-Free)	50 Units / Rail

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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

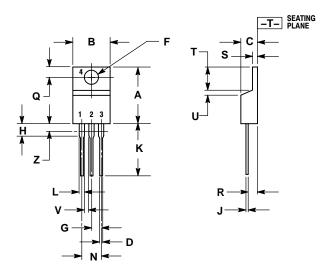
	Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTIC	CS (Note 2)		1		•		ı
Collector–Emitter Sustaining Voltage (I _C = 10 mA, I _B = 0)			V _{CEO(sus)}	400	_	-	Vdc
Collector Cutoff Current (V _{CES} = 700 Vdc) (V _{CES} = 700 Vdc, T _C = 125°C)			I _{CES}	_ _	- -	0.1 1.0	mAdc
Emitter Cutoff Current $(V_{EB} = 9.0 \text{ Vdc}, I_C = 0)$			I _{EBO}	-	_	100	μAdc
SECOND BREAKDOW	N						
Second Breakdown Co	llector Current with Base Forward	d Biased	I _{S/b}	See Figure 6			
Clamped Inductive SO	A with Base Reverse Biased		_	See Figure 7			
ON CHARACTERISTIC	S (Note 2)		1				
DC Current Gain ($I_C = 2.0 \text{ Adc}, V_{CE} = (I_C = 5.0 \text{ Adc}, V_{CE} =$			h _{FE}	8.0 5.0	- -	40 30	-
	4 Adc) 0 Adc) 0 Adc)		V _{CE(sat)}	1 1 1		1.0 2.0 3.0 3.0	Vdc
Base–Emitter Saturation Voltage (I_C = 2.0 Adc, I_B = 0.4 Adc) (I_C = 5.0 Adc, I_B = 1.0 Adc) (I_C = 5.0 Adc, I_B = 1.0 Adc, I_C = 100°C)		V _{BE(sat)}	- - -	- - -	1.2 1.6 1.5	Vdc	
DYNAMIC CHARACTE	RISTICS		-1		•	•	•
Current-Gain - Bandw (I _C = 500 mAdc, V _{CE}	idth Product = 10 Vdc, f = 1.0 MHz)		f _T	4.0	14	-	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0), f = 0.1 MHz)		C _{ob}	-	80	-	pF
SWITCHING CHARACT	TERISTICS		•		•	•	•
Resistive Load (Table	1)						
Delay Time			t _d	_	0.025	0.1	μs
Rise Time	$(V_{CC} = 125 \text{ Vdc}, I_{C} = 5.0 \text{ A},$		t _r	-	0.5	1.5	
Storage Time	$I_{B1} = I_{B2} = 1.0 \text{ A}, t_p = 25 \text{ μs},$ Duty Cycle ≤ 1.0%)		t _s	-	1.8	3.0]
Fall Time			t _f	-	0.23	0.7]
Inductive Load, Clam	ped (Table 1)		1		1		1
Voltage Storage Time	V_{CC} = 15 Vdc, I_{C} = 5.0 A V_{clamp} = 300 Vdc	$T_C = 25^{\circ}C$ $T_C = 100^{\circ}C$	t _{sv}	- -	1.2 1.6	2.0 3.0	μs
Crossover Time	$I_{B(on)} = 1.0 \text{ A}, I_{B(off)} = 2.5 \text{ A}$ $L_C = 200 \mu\text{H}$	$T_C = 25$ °C $T_C = 100$ °C	t _c	-	0.15 0.21	0.30 0.50	μS
Fall Time		$T_C = 25^{\circ}C$ $T_C = 100^{\circ}C$	t _{fi}	-	0.04 0.10	0.12 0.20	μs

^{2.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

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PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 **ISSUE AA**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.018	0.025	0.46	0.64	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
T	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

- STYLE 1:
 PIN 1. BASE
 2. COLLECTOR
 3. EMITTER
 4. COLLECTOR